

#### 185V 2A N-Channel Enhancement Mode Power MOSFET

#### **General Description**

BXP2N20 is Bridgelux high voltage MOSFET family based on advanced DMOS technology. This advanced MOSFET family has optimized on-state resistance, and also provides superior switching performance and higher avalanche energy strength. This device family is suitable for high efficiency switch mode power supplies.

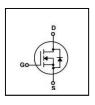
#### **FEATURES**

- RDSON≤1.80 Ω @Vgs=10V, Id=1A
- Excellent RDS(ON) and Low Gate Charge

Version: 2.1

- Fast switching capability
- · Lead free product is acquired

#### **SYMBOL**





SOT-23L

#### ASSEMBLY MESSAGE

Product Name	Marking	Package	Packaging
BXP2N20L	2N20 X	SOT-23L	Reel

### **ABSOLUTE MAXIMUM RATINGS** (Tc=25°C unless otherwise noted)

Parameter		Symbol	Rating BXP2N20L	Unit
Drain-Source Voltage		V <sub>DSS</sub>	185	V
Drain Current	Continuous (T <sub>C</sub> = 25°C)	- I <sub>D</sub>	2	А
Drain Current	Continuous (T <sub>C</sub> = 100°C)		1.2	А
Drain Current	Pulsed (Note1)	I <sub>DM</sub>	8	А
Gate-Source Voltage		V <sub>GSS</sub>	±30	V
Avalanche Energy	Single Pulse (Note2)	Eas	25	mJ
Peak Diode Recovery dv/dt (Note3)		dv/dt	5	V/ns
Power Dissipation (Note	T <sub>C</sub> =25°C		2	W
2)	Derate above 25°C	- P <sub>D</sub>	0.02	W/°C
Maximum Junction Temperature		TJ	150	°C
Storage Temperature Range		T <sub>STG</sub>	-55 to 150	°C

- Note: 1. Repetitive Rating: Pulse width limited by maximum junction temperature
  - 2. L=10mH,  $V_{DD}$ =50V, RG=25  $\Omega$ , Starting TJ = 25°C
  - 3.  $I_{SD} \le 2.0A$ , di/dt  $\le 300A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting TJ = 25°C



#### THERMAL CHARACTERISTICS

Parameter	Symbol	Max. BXP2N20L	Unit
Thermal Resistance, Junction-to-Ambient Re		100	°C / W

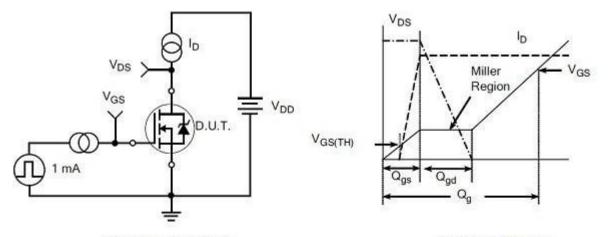
### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub>=25°C,unless otherwise Noted)

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	VGS=0V, ID=250μA	185	188		V
	I <sub>DSS</sub>	VDS=180V, VGS=0V			1	uA
Zero Gate Voltage Drain Current		VDS=140V, TC = 125°C			100	uA
Gate-Body Leakage Current, Forward		VGS=30V			100	nA
Gate-Body Leakage Current, Reverse	Igss	VGS=-30V			-100	nA
Breakdown Voltage Temperature	△BVDSS/	ID = 250 μA		0.25		V/°C
Coefficient	∆TJ		0.23	0.25		
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	VDS=VGS, ID=250μA	1		3	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	VGS=10V, ID=1A		1.15	1.80	Ω
DYNAMIC PARAMETERS						
Input Capacitance	C <sub>ISS</sub>	VDS=25V, VGS=0V, f=1.0MHz		125		pF
Output Capacitance	Coss			30		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			5.6		pF
SWITCHING PARAMETERS						
Turn-ON Delay Time	t <sub>D(ON)</sub>	VDD 400V ID 0 A VOC		7		ns
Turn-ON Rise Time	t <sub>R</sub>	VDD=100V, ID=2 A, VGS =		13		ns
Turn-OFF Delay Time	t <sub>D(OFF)</sub>	10V ,RG=10Ω (Note4,5)		26		ns
Turn-OFF Fall-Time	t <sub>F</sub>	(Note4,5)		8		ns
Total Gate Charge(Note5)	$Q_G$	VDS =160V, VGS =10V, ID		4.5		nC
Gate Source Charge	$Q_GS$	=2A		1.5		nC
Gate Drain Charge	Q <sub>GD</sub>	(Note4,5)		2		nC
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	IS=2A, VGS=0V			1.4	V
Diode Continuous Forward Current	ls				2	Α
Pulsed Drain-Source Current	I <sub>SM</sub>				8	Α
Reverse Recovery Time	t <sub>RR</sub>	VGS = 0 V, ISD = 2A		100		ns
Reverse Recovery Charge	Q <sub>RR</sub>	di/dt=100 A/µs (Note4,5)		0.3		uC

Note: 4. Pulse Test : Pulse width  $\leq 300\mu$ s, Duty cycle  $\leq 2\%$ 

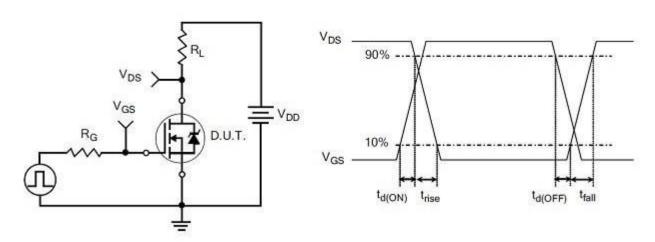
<sup>5.</sup> Essentially independent of operating temperature

### **TEST CIRCUITS AND WAVEFORMS**



Gate Charge Test Circuit

Gate Charge Waveform

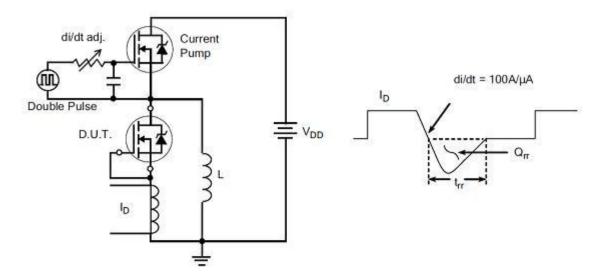


Resistive Switching Test Circuit

Resistive Switching Waveforms

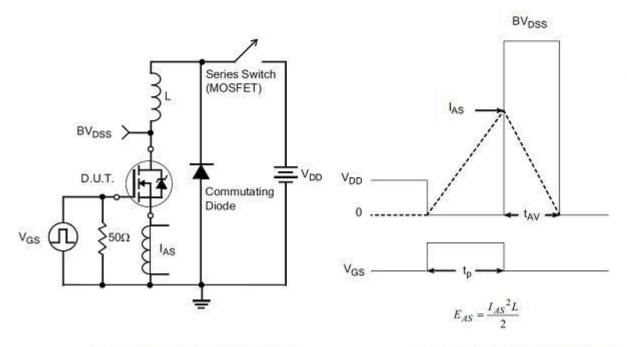


## TEST CIRCUITS AND WAVEFORMS(Cont.)



Diode Reverse Recovery Test Circuit

Diode Reverse Recovery Waveform

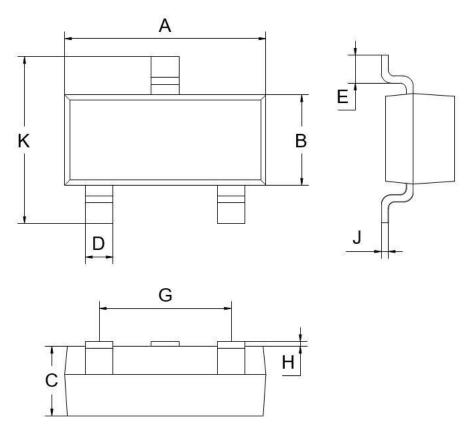


Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms







SOT-23L				
Dim	Dim Min Max			
Α	2.80	3.02		
В	1.50	1.70		
С	1.05	1.15		
D	0.28	0.5		
E	0.28	0.6		
G	1.80	2.00		
Н	0.02	0.10		
J	0.1	0.2		
К	2.70	3.00		
All Dimensions in mm				



# **Revision history**

## **Document revision history**

Date	Revision	Changes
1-Sep-2021	2.0	First release
5-Jan-2022	2.1	Update parameter



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